



UPDATE CHANGE NOTIFICATION # 20283

Generic Copy

Issue Date: 02-Aug-2014

TITLE: Qualification of NCP330, NCP340, and NCP341 with Palladium Coated Copper Wire

PROPOSED FIRST SHIP DATE: 02-Nov-2014 or earlier upon customer approval

AFFECTED CHANGE CATEGORY(S): Assembly Process

ADDITIONAL RELIABILITY DATA: Available. Contact your local ON Semiconductor Sales Office or Todd Manes <Todd.Manes@onsemi.com>

SAMPLES: Contact your local ON Semiconductor Sales Office

FOR ANY QUESTIONS CONCERNING THIS NOTIFICATION:
Contact your local ON Semiconductor Sales Office or <Shilpa.Rao@onsemi.com>

NOTIFICATION TYPE:

ON Semiconductor will consider this change approved unless specific conditions of acceptance are provided in writing within 90 days of receipt of this notice. To do so, contact <quality@onsemi.com>.

DESCRIPTION AND PURPOSE:

ON Semiconductor first issued FPCN20283 on October 30, 2013 announcing the qualification of Copper Wire for the NCP330MUTBG & NCP340MUTBG at ON Semiconductor's Seremban, Malaysia facility. UN20283 is an update notification informing our customers of the qualification of Palladium Coated Copper Wire for these devices at the same facility.

The NCP330, NCP340, and NCP341 are currently assembled at the ON Semiconductor Seremban, Malaysia facility with Au Wire. Upon the expiration of UN20283 or earlier with customer approval, these devices will be assembled with Palladium Coated Copper Wire. There is no change in package outline or electrical performance of the parts – they continue to fully meet datasheet specifications.



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RELIABILITY DATA SUMMARY:

Reliability Test Results:

All qualification requirements were successfully met.

Qual Vehicles

- NCP330MUTBG

#	Test	Name	Test Conditions	End Point Rea's	Test Results (rej/ss)				
					Read Point	Lot A	Lot B	Lot C	Lot Z
1	UHAST-PC	Precon + Unbiased High Accelerated Stress Test	T _{Amin} = 130, RH = 85%, Pressure = 18.8 psig	c = 0, Room (96)	96h	0/77	0/77	0/77	0/77
2	HTSL	High Temperature Storage Life	T _{Amin} = 150C	c = 0, Room	1008h	0/77	0/77	0/77	0/77
3	HAST+PC	Precon + High Accelerated Stress Test	T _{Amin} = 130C, RH = 85%, Pressure = 18.8 psig	c = 0, Room (96)	96h	0/77	0/77	0/77	0/77
4	TC+PC	Precon + Temperature Cycling	T _{Amin} = -65C, T _{Amax} = 150C	c = 0, Room (500)	500cyc	0/77	0/77	0/77	0/77
5	RSH	Resistance To Solder Heat	T _{Amin} = 260C	c = 0, Room (0)	Results	0/30	0/30	0/30	0/30

ELECTRICAL CHARACTERISTIC SUMMARY:

Electrical characteristics meet device specifications.

CHANGED PART IDENTIFICATION:

Following the announcement of this Update Notification devices will be assembled with Palladium coated Copper Wire at ON Semiconductor's existing Seremban facility. These devices will have date code of WW45, 2014 or earlier upon customer approval.

List of affected General Parts:

- NCP330MUTBG
- NCP340MUTBG
- NCP341MUTBG